L Number	Hits	Search Text	DB	Time stamp
1	2		USPAT;	2004/01/09 14:43
			US-PGPUB;	, 02, 03 11, 43
			EPO; JPO;	
			DERWENT;	
_	1986	MEMS and cavity	IBM_TDB	2002/10/00 17 72
	1 200	MADAS and Cavity	USPAT; US-PGPUB;	2003/10/22 17:50
			EPO; JPO;	
			DERWENT;	
	1		IBM TDB	
-	128	(438/55).CCLS.	USPĀT;	2003/10/22 17:26
			US-PGPUB;	
	İ		EPO; JPO;	
			DERWENT; IBM TDB	
-	188	(438/33).CCLS.	USPAT;	2003/10/22 17:27
	i		US-PGPUB;	2000, 20, 22 21.21
			EPO; JPO;	
			DERWENT;	
_	272	(438/64).CCLS.	IBM_TDB	
	""	(300/04).0003.	USPAT;	2003/10/22 17:27
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	168	(438/66).CCLS.	USPAT;	2003/10/22 17:28
			US-PGPUB;	
			EPO; JPO;	1
			DERWENT;	
-	2320	(438/106).CCLs.	IBM_TDB USPAT;	2003/10/22 17:29
		1	US-PGPUB;	2003/10/22 17:29
			EPO; JPO;	
	!		DERWENT;	
	664	/420/2001 0070	IBM_TDB	
-	664	(438/126).CCLS.	USPAT;	2003/10/22 17:30
1			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	i
-	1045	(438/118).CCLS.	USPAT;	2003/10/22 17:31
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	271	(438/110).CCLS.	IBM_TDB USPAT;	2003/10/22 17:32
			US-PGPUB;	2003/10/22 17:32
]			EPO; JPO;	
1			DERWENT;	
]_	202	(429/51) CCT C	IBM_TDB	
	202	(438/51).CCLS.	USPAT;	2003/10/22 17:32
			US-PGPUB;	
			EPO; JPO; DERWENT;	
[			IBM TDB	
-	593	(438/15).CCLS.	USPAT;	2003/10/22 17:32
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
-	742	(216/2).CCLS.	IBM_TDB USPAT;	2002/10/20 15 15
		· · · · · · · · · · · · · · · · · · ·	USPAT; US-PGPUB;	2003/10/22 17:47
			EPO; JPO;	
1			DERWENT;	
	1000	MDMO 1 /	IBM_TDB	
-	1737	MEMS and (cavity or cavities) and (cap or	USPAT;	2003/10/22 17:37
<u> </u>	İ	capped or capping or seal\$3 or cover\$3 or encapsulat\$3)	US-PGPUB;	
İ		οποαρουταίνο)	EPO; JPO;	
			DERWENT;	
		<del> </del>	IBM TDB	

1436   MEMS and (cavity or cavities) and (cap or capped or capping or seal\$3 or cover\$3 or encapsulat\$3) and (cut\$3 or etch\$3)   EPO; JPO; DERWENT; IBM TDB USFAT; US-PGPUB; EPO; JPO; DERWENT; IBM	17:47 18:29
Capped or capping or seal\$3 or cover\$3 or encapsulat\$3) and (cut\$3 or etch\$3)	17:47 18:29
DERWENT; IBM TDB USPAT; US-PGPUB; EPC, JPC; DERWENT; IBM TDB USPAT	17:47 18:29 17:48
- 215 (MEMS and (packag\$3)).ab.   IBM TDB USFAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JP	17:47 18:29 17:48
Comparison of the comparison	17:47 18:29 17:48
Comparison of the comparison	17:47 18:29 17:48
- 63 (MEMS and (cavity or cavities) and (cap or capped or capping or seal\$3 or cover\$3 or encapsulat\$3)).ab.  - 286 (216/11).CCLS.  - 425 (216/17).CCLS.  - 909 (216/20).CCLS.  - 644 (216/24).CCLS.  - 644 (216/24).CCLS.  - 644 (216/24).CCLS.  - 653 (MEMS and (cavity or cavities) and (cap or capping or seal\$3 or cover\$3 or encapsulat\$3) ab.  - 286 (216/11).CCLS.  - 286 (216	18:29 17:48
- 63 (MEMS and (cavity or cavities) and (cap or capped or capping or seal\$3 or cover\$3 or encapsulat\$3).ab.  - 286 (216/11).CCLS.  - 425 (216/17).CCLS.  - 909 (216/20).CCLS.  - 644 (216/24).CCLS.  - 644 (216/24).CCLS.  - 644 (216/24).CCLS.  - Capped or capping or seal\$3 or cover\$3 or encapsulat\$3).ab.  - DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JP	18:29 17:48
Capped or capping or seal\$3 or cover\$3 or cappus;   Capped or capping or seal\$3 or cover\$3 or encapsulat\$3).ab.   Capped or capping or seal\$3 or cover\$3 or encapsulat\$3).ab.   Capped or capping or seal\$3 or cover\$3 or encapsulat\$3).ab.   Capped or capping or seal\$3 or cover\$3 or ePO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; J	18:29 17:48
MEMS and (cavity or cavities) and (cap or capped or capping or seal\$3 or cover\$3 or encapsulat\$3)).ab.	18:29 17:48
Capped or capping or seal\$3 or cover\$3 or encapsulat\$3)).ab.  286 (216/11).CCLS.  (216/11).CCLS.  (216/17).CCLS.  (216/17).CCLS.  (216/17).CCLS.  (216/20).CCLS.  (216/24).CCLS.  (216/24).CCLS.  (216/24).CCLS.  (216/24).CCLS.  (216/25) or cover\$3 or US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IS-PGPUB; EPO; J	18:29 17:48
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO;	17:48
- 286 (216/11).CCLS.   IBM_TDB   USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB   USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB   USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB   USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB   USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB   USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB   USPAT; US-PGPUB; EPO; JPO; USPAT; US-PGPUB; EPO; JPO;	17:48
- 425 (216/11).CCLS.  - 425 (216/17).CCLS.  - 425 (216/17).CCLS.  - 425 (216/17).CCLS.  - 909 (216/20).CCLS.  - 644 (216/24).CCLS.  - 644 (216/24).CCLS.  - 644 (216/24).CCLS.  - 645 (216/17).CCLS.  - 1003/10/22  - 2003/10/22  - 2003/10/22  - 2003/10/22  - 2003/10/22  - 2003/10/22  - 2003/10/22  - 2003/10/22  - 2003/10/22  - 2003/10/22  - 2003/10/22  - 2003/10/22  - 2003/10/22  - 2003/10/22  - 2003/10/22  - 2003/10/22	17:48
- 425 (216/17).CCLS. US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO;	17:48
- 425 (216/17).CCLS. EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO;	
DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO;	
- 425 (216/17).CCLS. IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	
- 425 (216/17).CCLS. USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO;	
- 909 (216/20).CCLS.  909 (216/20).CCLS.  (216/20).CCLS.  (216/20).CCLS.  (216/20).CCLS.  (216/20).CCLS.  (216/20).CCLS.  (216/20).CCLS.  (2003/10/22  (216/24).CCLS.  (216/24).CCLS.  (216/24).CCLS.	
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; USPAT; US-PGPUB; USPAT; US-PGPUB; EPO; JPO;	17:49
- 909 (216/20).CCLS. IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO;	17:49
G44 (216/24).CCLS.  USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; USPĀT; US-PGPUB; EPO; JPO;	17:49
- 644 (216/24).CCLS. US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO;	17:49
EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO;	1
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO;	
- 644 (216/24).CCLS.   IBM TDB   USPĀT; US-PGPUB; EPO; JPO;	
USPĀT; US-PGPUB; EPO; JPO; 2003/10/22	
US-PGPUB; EPO; JPO;	17:50
DERWENT;	
- 2311 MEMS and (cavity or recess) IBM TDB USPAT; 2003/10/22	10 15
USPAT; 2003/10/22 US-PGPUB;	18:17
EPO; JPO;	
DERWENT;	
- 480 (216/33).CCLS. IBM_TDB	1
USPAT; 2003/10/22	17:56
US-PGPUB;	ĺ
EPO; JPO;	
DERWENT; IBM TDB	İ
- 123 (216/36).CCLS. USPAT; 2003/10/22	17.54
US-PGPUB;	17.54
EPO; JPO;	}
DERWENT;	
- 10 ((216/33).CCLS.) and mems   IBM_TDB   USPAT: 2003/10/22	
1 1 2003/10/22	17:54
US-PGPUB; EPO; JPO;	1
DERWENT;	ļ
TRM TDP	
80 (((438/25).CCLS.) or ((438/55).CCLS.) or USPAT; 2003/10/22	18:00
(438/64), CCLS.) or $(438/64)$ , CCLS.) or $(438/64)$	
((438/66).CCLS.) or ((438/106).CCLS.) or EPO; JPO;	
((438/127).CCLS.) or ((438/126).CCLS.) or DERWENT; ((438/118).CCLS.) or ((438/110).CCLS.) or IBM TDB	
((438/51).CCLS.) or ((438/110).CCLS.) or IBM_TDB	
MEMS	
141 (((216/2).CCLS.) or ((216/11).CCLS.) or USPAT; 2004/01/09 1	2.16
((216/17).CCLS.) or $((216/20).CCLS.)$ or $(HS=DCDUD.)$	_ · · · ·
((216/24).CCLS.) or ((216/33).CCLS.) or EPO; JPO;	
((216/36).CCLS.)) and MEMS DERWENT;	
IBM TDB	

Comparison of the comparison					
(438/66).CCLS.) or ((438/126).CCLS.) or ((438/127).CCLS.) or ((438/127).CCLS.) or ((438/118).CCLS.) or ((438/118).CCLS.) or ((438/118).CCLS.) or ((248/118).CCLS.) or ((218/37).CCLS.) or ((218/37).CCLS.) or ((216/37).CCLS.) or	-	215			2003/10/22 18:00
(438/127).CCLS.) or ((438/128).CCLS.) or ((438/128).CCLS.) or ((438/138).CCLS.) or ((438/138).CCLS.) or ((438/138).CCLS.) and WHENDER ((438/138).CCLS.) or ((216/24).CCLS.) or ((216/24).CCLS.) or ((216/24).CCLS.) or ((216/24).CCLS.) or ((216/33).CCLS.) or ((216/34).CCLS.) or ((216/33).CCLS.) or ((216/34).CCLS.) or ((216/33).CCLS.) or ((216/34).CCLS.) or ((216/34).C			((438/33).CCLS.) or ((438/64).CCLS.) or		
(438/118).CCLS.) or ((438/110).CCLS.) or ((438/116).CCLS.) and (438/55).CCLS.) or ((1216/22).CCLS.) and (1216/12).CCLS.) or ((1216/23).CCLS.) or ((1216/24).CCLS.) or (1216/24).CCLS.) or (1216/24).CCLS.) or ((1216/24).CCLS.) or ((1216/24).CC			((438/66).CCLS.) or ((438/106).CCLS.) or		
((438/51).CCLS.) or ((438/15).CCLS.) and KEMS) or (((216/11).CCLS.) or ((216/11).CCLS.) or ((216/27).CCLS.) or ((216/27).CCLS.) or ((216/27).CCLS.) or ((216/28).CCLS.) or ((216/28).CCLS.) or ((216/36).CCLS.)) and (EMS)  - 20 ((wafer adj bonding) or (wafer adj cap84).ti. and MEMS)  - 1567 MEMS and (cavity or recess) and cap\$4  - 49 MEMS and (cavity or recess) and wafer adj cap84).ti. uspar: U	-		((438/127).CCLS.) or ((438/126).CCLS.) or		
MEMS   Or ((((216/2), CCLS.) or ((216/21), CCLS.) or ((216/21), CCLS.) or ((216/21), CCLS.) or ((216/23), CCLS.) or ((216/33), CCLS.) or ((216/32), CCLS.)	i		((438/118).CCLS.) or ((438/110).CCLS.) or	IBM_TDB	
(216/11).CCLS.) or ((216/21).CCLS.) or ((216/20).CCLS.) or ((216/20).CCLS.) or ((216/20).CCLS.) or ((216/34).CCLS.) or ((216/34).CCLS.) or ((216/34).CCLS.)) and MEMS (Cap\$4).ti. and MEMS (Cap\$4).ti. and MEMS (Cap\$4).ti. and MEMS (Cap\$4).ti. and MEMS (Cap\$4) (Cap\$4).ti. and MEMS (Cap\$4)			((438/51).CCLS.) or ((438/15).CCLS.)) and		
(216/20).CCLS.) or ((216/24).CCLS.) or ((216/24).CCLS.) or ((216/33).CCLS.) or ((216/36).CCLS.)) and MEMS)  20 ((wafer adj) bonding) or (wafer adj) USPAT; US-RCPUB; DERMENT) IN TOB USPAT; US-RCPUB; DERMENT) IN TOB USPAT; US-RCPUB; DERMENT IN TOB USPAT; US-RCPUB; DERMENT; IN TOB USPAT; US-RCPUB; DERMENT; IN TOB USPAT; US-RCPUB; DERMENT; IN TOB USPAT; US-RCPUB; DERMENT; IN TOB USPAT; US-RCPUB; DERMENT; IN TOB USPAT; US-RCPUB; DERMENT; IN TOB USPAT; US-RCPUB; DERMENT; IN TOB USPAT; US-RCPUB; DERMENT; IN TOB USPAT; US-RCPUB; DERMENT; IN TOB USPAT; US-RCPUB; DERMENT; US-RCPUB; DERM			MEMS) or ((((216/2).CCLS.) or		
C(216/33).CCLS.) or ((216/36).CCLS.) and   MEMS   ((wafor adj bonding) or (wafer adj US-PGFUB; EFC; JPC; DEARMENT; IDM_IDM   USPAT; US-PGFUB; EFC; JPC; DEARMENT; IDM_IDM_IDM_IDM_IDM_IDM_IDM_IDM_IDM_IDM_			((216/11).CCLS.) or ((216/17).CCLS.) or		
MEMS   Cap\$4)   Li. and NEMS   Cap\$4   Li. and Nems   Cap\$4)   Li. and Nems   Cap\$4   Li. and Nems   Cap\$4)   Li. and Nems   Cap\$4)   Li. and Nems   Cap\$4)   Li. and Nems   Cap\$4	İ		((216/20).CCLS.) or ((216/24).CCLS.) or		
-					
Cap\$4)	_	20			
Total   Tota		20	((water ad) bonding) or (water ad)		2003/10/22 18:18
Temper			caps4/).cr. and MEMS		
TEM TDB					:
1567   NEMS and (cavity or recess) and cap\$4   USFAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; PEO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB;					
US-PCPUB; EPO; JPO; DERMENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; US-PGPUB; EPO; JPO; DERMENT; US-PGPUB; EPO; JPO; DER	-	1567	MEMS and (cavity or recess) and cans4		2003/10/22 18-27
MEMS and (cavity or recess) and (wafer adj cap\$4)		1 2007	indicately of recess, and capta	· ·	2003/10/22 18:3/
Second Content of Caps   Cap					
MEMS and (cavity or recess) and (wafer adj cap\$4)				1	ļ
MEMS and (cavity or recess) and (wafer adj USPÄT; US-PGPUB; EPG; JPG; DERWENT; IBM TDB USPÄT; USPÄT; USPÄT; USPÄT; USPÄT; USPÄT; USPÄT; USPÄT; USPÄT; USPÄT; USPÄT; USPÄT; USPÄT; USPÄT; USPÄT; USPÄ				_	
Cap\$4)	-	49	MEMS and (cavity or recess) and (wafer adi		2003/10/22 18:20
### Page				· ·	1 -000, 10, 22 10.20
DERMENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB USPAT; USPA					]
MEMS and (cavity or recess) and (wafer near3 cap\$4)   IBM TDB   US-PGPUB; EPO; JPO; DERWENT; IBM TDB   USPAT; US-PGPUB; EPO; JPO; DERWENT;					1
SPAT;   SPAT		1			
near3 cap\$4)	-	99	MEMS and (cavity or recess) and (wafer	_	2003/10/22 18:27
Carry   Carr			near3 cap\$4)		
TBM TDB				EPO; JPO;	
27   (MEMS and package).ti.				DERWENT;	
Section   Sect	-			IBM_TDB	
Sep. jpc; Derwent; IEM TOB USPAT; US-PGPUB; EPO; Jpc; Derwent; I	j -	27	(MEMS and package).ti.	USPAT;	2003/10/22 18:28
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IEM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IEM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IEM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IEM TDB USPAT; US				US-PGPUB;	
BM TDB		ļ		EPO; JPO;	
- 803 (257/433).CCLS.  816 (257/443).CCLS.  816 (257/443).CCLS.  817 (257/443).CCLS.  818 (257/443).CCLS.  819 (257/443).CCLS.  819 (257/433).CCLS.) or ((257/443).CCLS.)  819 (257/433).CCLS.) or ((257/443).CCLS.)  810 (257/433).CCLS.) or ((257/443).CCLS.)  810 (257/433).CCLS.) or ((257/443).CCLS.)  810 (257/433).CCLS.) or ((257/443).CCLS.)  810 (257/433).CCLS.) or ((257/443).CCLS.)  810 (257/433).CCLS.) or ((257/443).CCLS.)  810 (257/433).CCLS.) or ((257/443).CCLS.)  810 (257/433).CCLS.) or ((257/443).CCLS.)  811 (257/433).CCLS.) or ((257/443).CCLS.)  812 (2003/10/22 18:32  813 (2003/10/22 18:32  814 (257/433).CCLS.  815 (257/433).CCLS.  816 (257/433).CCLS.  817 (257/433).CCLS.  818 (2003/10/22 18:32  819 (2003/10/22 18:33  82003/10/22 18:33				1	
US-FGPUB; EPO; JPO; DERWENT; IBM TDB USFAT; US-PGPUB; EPO; JPO; DERWENT; EPO; JPO; DERWENT;		000	(057 /400) cor c	· —	
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- 816 (257/443).CCLS. USPĀT; US-PGPUB; EPO, JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO, JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO, JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; ISM TDB					
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- 1596 ((257/433).CCLS.) or ((257/443).CCLS.)  - 561 (257/466).CCLS.  - 561 (257/466).CCLS.  - 334 MEMS and (cavity or recess) and cap\$4 and dic\$3  - 2 ("5323051").PN.  - 154 (438/25).CCLS.    IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;				1	
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- 2 ("5323051").PN. USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;					
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